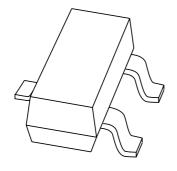
## **DISCRETE SEMICONDUCTORS**

# DATA SHEET



**PBSS4160T**60 V, 1 A
NPN low V<sub>CEsat</sub> (BISS) transistor

Product data sheet Supersedes data of 2003 Jun 24 2004 May 12



# 60 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

## **PBSS4160T**

### **FEATURES**

- Low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability I<sub>C</sub> and I<sub>CM</sub>
- High efficiency, reduces heat generation
- Reduces printed-circuit board area required
- Cost effective replacement for medium power transistor BCP55 and BCX55.

## **APPLICATIONS**

- Major application segments:
  - Automotive 42 V power
  - Telecom infrastructure
  - Industrial.
- Power management:
  - DC-to-DC conversion
  - Supply line switching.
- · Peripheral driver
  - Driver in low supply voltage applications (e.g. lamps and LEDs)
  - Inductive load driver (e.g. relays, buzzers and motors).

## **DESCRIPTION**

NPN low  $V_{\text{CEsat}}$  transistor in a SOT23 plastic package. PNP complement: PBSS5160T.

## **MARKING**

TYPE NUMBER	MARKING CODE(1)
PBSS4160T	*U5

## Note

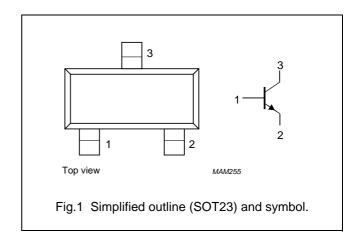
- 1. \* = p: made in Hong Kong
  - \* = t: made in Malaysia
  - \* = W: made in China.

### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	60	V
I <sub>C</sub>	collector current (DC)	1	Α
I <sub>CM</sub>	peak collector current	2	Α
R <sub>CEsat</sub>	equivalent on-resistance 25		$m\Omega$

## **PINNING**

PIN	DESCRIPTION
1	base
2	emitter
3	collector



## ORDERING INFORMATION

TYPE NUMBER	PACKAGE			
TIFE NOMBER	NAME DESCRIPTION VERSION			
PBSS4160T	<ul> <li>plastic surface mounted package; 3 leads</li> </ul>		SOT23	

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# 60 V, 1 A NPN low $V_{CEsat}$ (BISS) transistor

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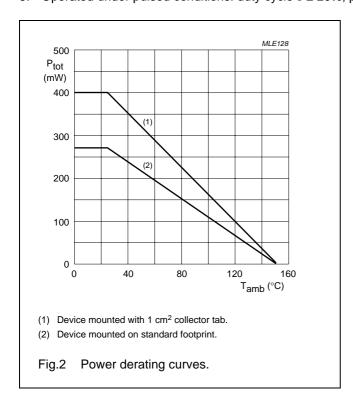
### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	80	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	60	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	5	V
Ic	collector current (DC)	note 1	_	0.9	Α
		note 2	_	1	Α
I <sub>CM</sub>	peak collector current	t = 1 ms or limited by T <sub>j(max)</sub>	_	2	Α
I <sub>B</sub>	base current (DC)		_	300	mA
I <sub>BM</sub>	peak base current	$t_p \le 300~\mu s;~\delta \le 0.02$	_	1	Α
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	270	mW
		T <sub>amb</sub> ≤ 25 °C; note 2	_	400	mW
		T <sub>amb</sub> ≤ 25 °C; notes 1 and 3	_	1.25	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>j</sub>	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

## **Notes**

- 1. Device mounted on an FR4 printed-circuit board, single-sided copper, tin-plated, standard footprint.
- 2. Device mounted on an FR4 printed-circuit board, single-sided copper, tin-plated, 1 cm<sup>2</sup> collector mounting pad.
- 3. Operated under pulsed conditions: duty cycle  $\delta \leq$  20%, pulse width  $t_p \leq$  10 ms.



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## 60 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

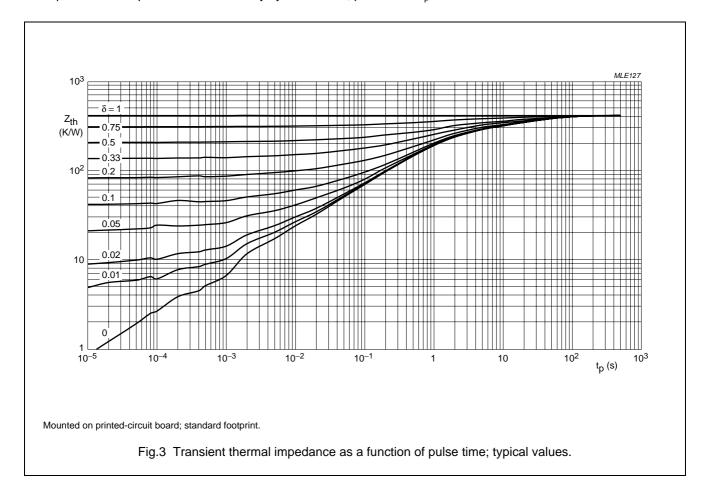
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## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to	in free air; note 1	465	K/W
	ambient	in free air; note 2	312	K/W
		in free air; notes 1 and 3	100	K/W

## **Notes**

- 1. Device mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint.
- 2. Device mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and 1 cm<sup>2</sup> collector mounting pad.
- 3. Operated under pulsed conditions: duty cycle  $\delta \le 20\%$ , pulse width  $t_p \le 10$  ms.



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## 60 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

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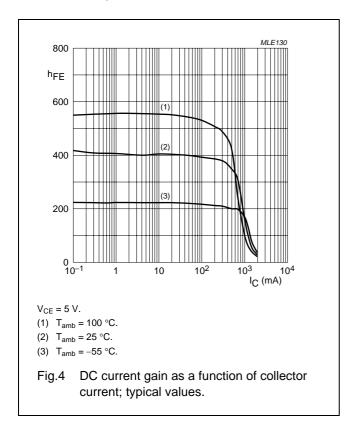
## **CHARACTERISTICS**

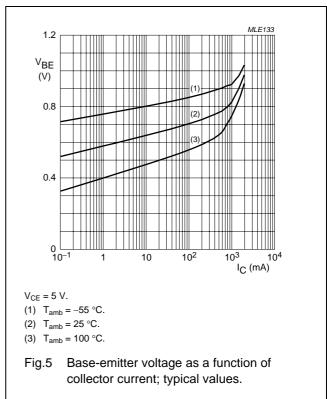
 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 60 V; I <sub>E</sub> = 0 A	_	-	100	nA
		V <sub>CB</sub> = 60 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 150 °C	_	_	50	μΑ
I <sub>CES</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 60 V; V <sub>BE</sub> = 0 A	_	-	100	nA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = 5 V; I <sub>C</sub> = 0 A	_	-	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 mA	250	400	-	
		$V_{CE} = 5 \text{ V}; I_{C} = 500 \text{ mA}; \text{ note 1}$	200	350	-	
		V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 A; note 1	100	150	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 100 mA; I <sub>B</sub> = 1 mA	_	90	110	mV
		$I_C = 500 \text{ mA}; I_B = 50 \text{ mA}$	_	110	140	mV
		I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA; note 1	_	200	250	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	I <sub>C</sub> = 1 A; I <sub>B</sub> = 50 mA	_	0.95	1.1	V
R <sub>CEsat</sub>	equivalent on-resistance	I <sub>C</sub> = 1 A; I <sub>B</sub> = 100 mA; note 1	_	200	250	mΩ
V <sub>BEon</sub>	base-emitter turn-on voltage	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 1 A	_	0.82	0.9	V
f <sub>T</sub>	transition frequency	$I_C = 50 \text{ mA}; V_{CE} = 10 \text{ V};$ f = 100 MHz	150	220	_	MHz
C <sub>c</sub>	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0 \text{ A}; f = 1 \text{ MHz}$	_	5.5	10	pF

## Note

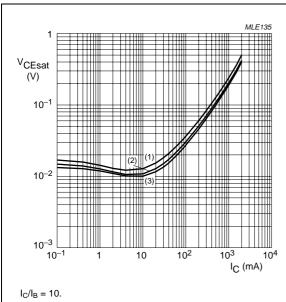
1. Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 





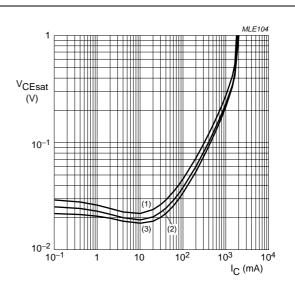
# 60 V, 1 A NPN low $V_{CEsat}$ (BISS) transistor

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- (1)  $T_{amb} = 100 \, ^{\circ}C$ .
- (2)  $T_{amb} = 25 \, ^{\circ}C$ .
- (3)  $T_{amb} = -55 \, ^{\circ}C$ .

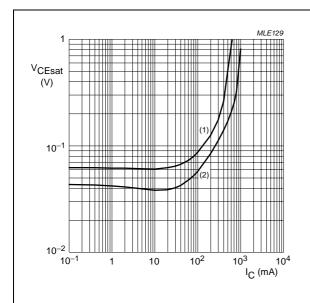
Fig.6 Collector-emitter saturation voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 20$ .

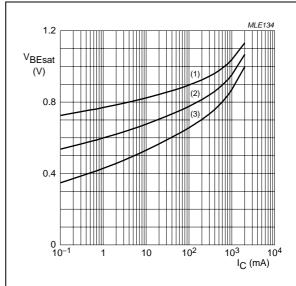
- (1)  $T_{amb} = 100 \, ^{\circ}C$ .
- (2) T<sub>amb</sub> = 25 °C.
- (3)  $T_{amb} = -55 \, ^{\circ}C$ .

Fig.7 Collector-emitter saturation voltage as a function of collector current; typical values.



- $T_{amb} = 25 \, ^{\circ}C.$
- (1)  $I_C/I_B = 100$
- (2)  $I_C/I_B = 50$ .

Fig.8 Collector-emitter saturation voltage as a function of collector current; typical values.



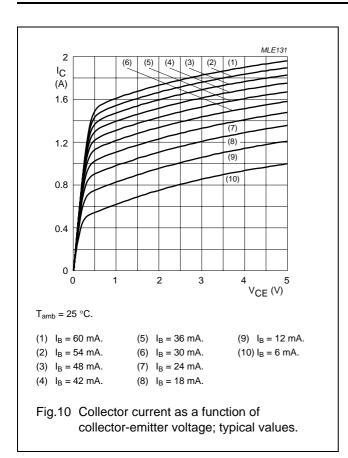
 $I_{\rm C}/I_{\rm B} = 20.$ 

- (1)  $T_{amb} = -55 \, ^{\circ}C$ .
- (2)  $T_{amb} = 25 \, ^{\circ}C$ .
- (3)  $T_{amb} = 100 \, ^{\circ}C$ .

Fig.9 Base-emitter saturation voltage as a function of collector current; typical values.

# 60 V, 1 A NPN low $V_{CEsat}$ (BISS) transistor

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RCEsat  $(\Omega)$   $10^2$   $10^{-1}$   $10^{$ 

Fig.11 Equivalent on-resistance as a function of collector current; typical values.

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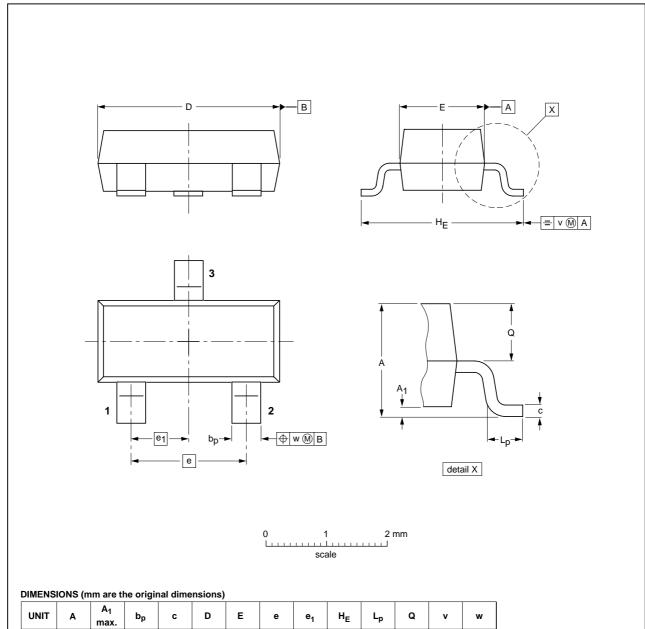
## 60 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

**PBSS4160T** 

## **PACKAGE OUTLINE**



SOT23



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION ISSUE DA	
SOT23		TO-236AB				<del>-04-11-04-</del> 06-03-16

1.9

0.45

0.55

0.2

0.1

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0.38

0.9

## 60 V, 1 A NPN low V<sub>CEsat</sub> (BISS) transistor

PBSS4160T

### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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